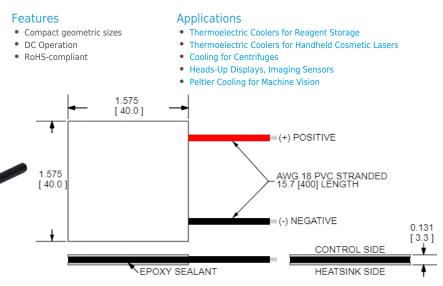
Ceramic Plate Series CP14-199-045-L1-EP-W400MM MFG Part Number: 387001715

Ceramic Plate Series Thermoelectric Cooler

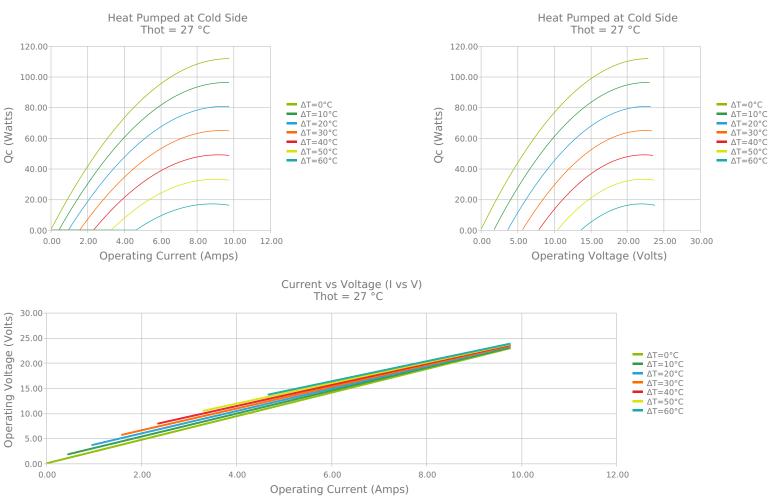
The CP14-199-045-L1-EP-W400MM is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 111.8 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at Qc = 0.

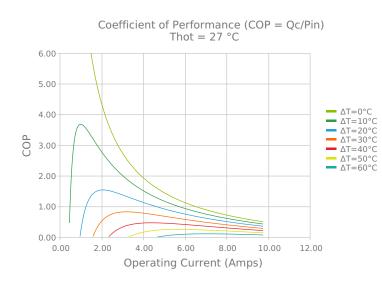


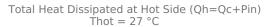
CERAMIC MATERIAL: Al₂O₃ SOLDER CONSTRUCTION: 138°C, BiSn INCHES [MM] Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

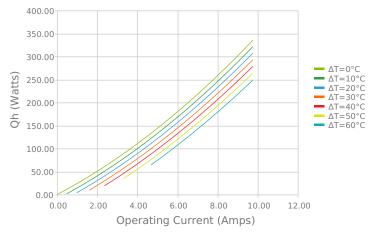
ELECTRICAL AND THERMAL PERFORMANCE

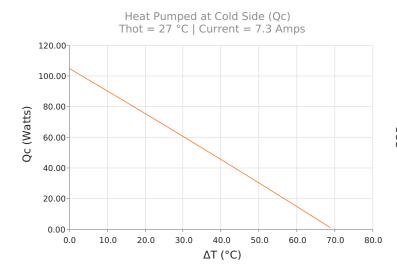
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

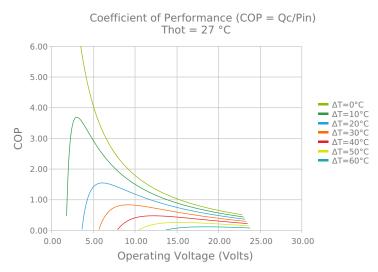




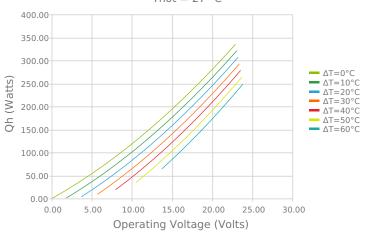




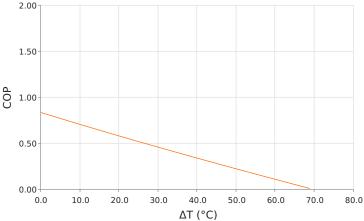




Total Heat Dissipated at Hot Side (Qh=Qc+Pin) Thot = 27 $^{\circ}C$



Coefficient of Performance (COP = Qc/Pin) Thot = 27 °C | Current = 7.3 Amps



SPECIFICATIONS*

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	111.8 Watts	115.2 Watts	121.2 Watts
ΔTmax (Qc = 0)	70.5°C	73.5°C	78.8°C
lmax (I @ ΔTmax)	8.6 Amps	8.6 Amps	8.5 Amps
Vmax (V @ ΔTmax)	21.7 Volts	22.6 Volts	24.1 Volts
Module Resistance	2.35 Ohms	2.44 Ohms	2.63 Ohms
Max Operating Temperature	80 °C		
Weight	25.0 gram(s)		

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	3.327 ±0.025 mm 0.131 ± 0.0010 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Ероху	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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